Amendments to the Claims:

Claim 1 has been amended. Please note that all claims currently pending and under consideration in the referenced application are shown below. This listing of claims will replace all prior versions and listings of claims in the application.

Listing of Claims:

1. (Previously presented) A method for forming an interposer substrate, comprising:

providing a rectangular, substantially planar substrate ~~comprising~~ consisting of a dielectric material;

forming an elongated interconnect slot comprising a plurality of longitudinally adjacent segments separated by at least one transversely extending crosspiece, the elongated interconnect slot being sized and configured for alignment with bond pads on a semiconductor die when the semiconductor die is placed on the substantially planar substrate, the bond pads being accessible through the interconnect slot.

2. (Previously presented) The method of claim 1, further comprising forming the interconnect slot by milling through the substrate and the at least one transversely extending crosspiece comprises at least one unmilled portion of the substrate lying intermediate opposing ends of the interconnect slot.

3. (Previously presented) The method of claim 2, further comprising producing filleted side edges on the at least one transversely extending crosspiece during the milling.

4. (Withdrawn) The method of claim 1, wherein forming the elongated interconnect slot comprises forming a unitary elongated interconnect slot and forming the at least one transversely extending crosspiece by bonding a segment of material transversely across the interconnect slot at a location intermediate opposing ends thereof.

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5. (Withdrawn) The method of claim 4, wherein forming the at least one transversely extending crosspiece comprises forming a tape segment coated with an adhesive on opposing sides thereof and adhering the tape segment to a surface of the substantially planar substrate.

6. (Withdrawn) The method of claim 1, wherein forming the elongated interconnect slot comprises forming a unitary elongated interconnect slot, forming an "I"-shaped segment of material and bonding a head portion of the "I"-shaped segment to the substrate on one side of the interconnect slot and a foot portion of the "I"-shaped segment to the substrate on an opposing side of the interconnect slot with a body portion of the "I"-shaped segment extending transversely thereacross to form the at least one transversely extending crosspiece.

7. (Withdrawn) The method of claim 6, further comprising forming the "I"-shaped segment as a film having an adhesive coating on opposing sides thereof.

8. (Withdrawn) The method of claim 6, further comprising forming the "I"-shaped segment as a substantially rigid plastic segment.

9. (Withdrawn) The method of claim 1, wherein forming the elongated interconnect slot comprises forming a unitary elongated interconnect slot, forming a "T"-shaped element having a body and a cap, extending the body into the interconnect slot in contact with opposing sides thereof and bonding legs of the cap extending transversely to the interconnect slot over a surface of the substrate thereto to form the at least one transversely extending crosspiece.

10. (Withdrawn) The method of claim 1, wherein forming the elongated interconnect slot comprises forming a unitary elongated interconnect slot, forming a tape segment of a polymeric material containing a reinforcement material, disposing the tape segment transversely across the interconnect slot and bonding the tape segment to a surface of the substrate.

11. (Withdrawn) The method of claim 1, wherein forming the elongated interconnect slot comprises forming a unitary elongated interconnect slot, interposing a bar of material transversely between opposing sides of the interconnect slot and bonding the bar thereto.

12. (Previously presented) The method of claim 1, further comprising forming the elongated interconnect slot to a length of about 67% or more of a length of the substrate.

13. (Previously presented) The method of claim 12, further comprising forming the elongated interconnect slot to a length of about 70 to 80% of a length of the substrate.

14. (Previously presented) The method of claim 1, further comprising locating the at least one transversely extending crosspiece substantially at a longitudinal midpoint of the interconnect slot.